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POWERTAP II Switch-mode Power Rectifier

These state-of-the-art devices use the Schottky Barrier principle with a platinum barrier metal.

Features

- Dual Diode Construction May Be Paralleled for Higher Current Output
- Guardring for Stress Protection
- Low Forward Voltage
- 150°C Operating Junction Temperature
- Pb-Free Package is Available*

Mechanical Characteristics:

- Case: Epoxy, Molded with metal heatsink base
- Weight: 80 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant
- Top Terminal Torque: 25–40 lb–in max
- Base Plate Torques: See procedure given in the Package Outline Section

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	60 60	V
Average Rectified Forward Current (Rated V _R , T _C = 140°C) Per Leg Per Device	I _{F(AV)}	100 200	A
$\begin{array}{llllllllllllllllllllllllllllllllllll$	I _{FRM}	200	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	1500	A
Peak Repetitive Reverse Current (2.0 μs, 1.0 kHz) Per Leg	IRRM	2.0	A
Storage Temperature Range	T _{stg}	-55 to +150	°C
Operating Junction Temperature	TJ	-55 to +150	°C
Voltage Rate of Change (Rated V_R)	dv/dt	10,000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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SCHOTTKY BARRIER RECTIFIER 200 AMPERES, 60 VOLTS

POWERTAP II CASE 357C PLASTIC

MARKING DIAGRAM



B20060T	= Specific Device Code
MCC	= Mold Compound Code
А	= Assembly Location
YY	= Year
WW	= Work Week
G	= Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
MBRP20060CT	POWERTAP II	25 Units/Tray
MBRP20060CTG	POWERTAP II (Pb–Free)	25 Units/Tray

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THERMAL CHARACTERISTICS (Per Leg)

Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.6	°C/W

Instantaneous Forward Voltage (Note 1) ($i_F = 200 \text{ Amps}, T_J = 25^{\circ}C$) ($i_F = 200 \text{ Amps}, T_J = 100^{\circ}C$)	v _F	0.91 0.80	V
Instantaneous Reverse Current (Note 1) (Rated dc Voltage, T _J = 125°C) (Rated dc Voltage, T _J = 25°C)	İR	50 0.5	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.







Figure 9. Test Circuit for Repetitive Reverse Current

MAXIMUM MECHANICAL RATINGS

Terminal Penetration:	0.235 max
Terminal Torque:	25–40 in-lb max
Mounting Torque — Outside Holes:	30–40 in-lb max
Mounting Torque — Center Hole:	8–10 in-lb max
Seating Plane Flatness	1 mil per in. (between mounting holes)

POWERTAP MECHANICAL DATA **APPLIES OVER OPERATING TEMPERATURE**



SINK

Note: While the POWERTAP is capable of sustaining these vertical and levered tensions, the intimate contact between POWERTAP and heat sink may be lost. This could lead to thermal runaway. The use of very flexible leads is recommended for the anode connections. Use of thermal grease is highly recommended.

MOUNTING PROCEDURE

The POWERTAP package requires special mounting considerations because of the long longitudinal axis of the copper heat sink. It is important to follow the proper tightening sequence to avoid warping the heat sink, which can reduce thermal contact between the POWERTAP and heat sink. A O A

	2-3 TURNS	2-0		2	2-3 TURNS
STEP 1:					¥
Locate the POWERTAP on the heat sink and					
start mounting bolts into the threads by hand		POWER		TAP	
	K	HEAT		SINK	
		0			
		EINC		~	
STEP 2:				í í litera í	
Finger tighten the center bolt. The bolt may					
catch on the threads of the heat sink so it is		POWER		TAP	
important to make sure the face of the bolt or		HEAT	Y I	SINK	
washer is in contact with the surface of the					
POWERTAP.	$\langle \cdot \rangle$				
STED 3.	5-10 IN-LB	FING			5-10 IN-LB
Tighten each of the end bolts between 5 to 10					
in-lb.		POWER		TAP	
S'A		HEAT		SINK	
	<u>K</u> /				
STED 4.	5–10 IN-LB	8-	10 IN-LB	⁵	5–10 IN-LB
SILP 4: Tighten the center bolt between 8 to 10 in lb					
righten the center bolt between 8 to 10 m-10.		POWER		TAP	
		ΗΕΔΤ		SINK	
	K/			UNIX	
	30-40 IN-LB	8-	10 IN-LB	3	0-40 IN-LB
STEP 5:					_ \
Finally, tighten the end bolts between 30 to 40		POWER		ТАР	
IN-ID.		FOWER	_//	IAP	

HEAT

PACKAGE DIMENSIONS

CASE 357C-03 POWERTAP PLASTIC PACKAGE





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